

Semiconductor devices - Micro-electromechanical devices - Part 25: Silicon based MEMS fabrication technology - Measurement method of pull-press and shearing strength of micro bonding area

EESTI STANDARDI EESSÕNA

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English Version

**Semiconductor devices - Micro-electromechanical devices -
Part 25: Silicon based MEMS fabrication technology -
Measurement method of pull-press and shearing strength of
micro bonding area
(IEC 62047-25:2016)**

Dispositifs à semiconducteurs - Dispositifs
microélectromécaniques - Partie 25: Technologie de
fabrication de MEMS à base de silicium - Méthode de
mesure de la résistance à la traction-compression et au
cisaillement d'une micro zone de brasure
(IEC 62047-25:2016)

Halbleiterbauelemente - Bauelemente der
Mikrosystemtechnik - Teil 25: Siliziumbasierte MEMS-
Herstellungstechnologie - Messverfahren zur Zug-Druck-
und Scherfestigkeit gebondeter Flächen im
Mikrometerbereich
(IEC 62047-25:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 47F/249/FDIS, future edition 1 of IEC 62047-25, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-25:2016.

The following dates are fixed:

- latest date by which the document has to be (dop) 2017-07-03
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publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2019-10-03
standards conflicting with the
document have to be withdrawn

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-1	-	Semiconductor devices - Micro-electromechanical devices - Part 1: Terms and definitions	EN 62047-1	-
ISO 10012	-	Measurement management systems - Requirements for measurement processes and measuring equipment	EN ISO 10012	-

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